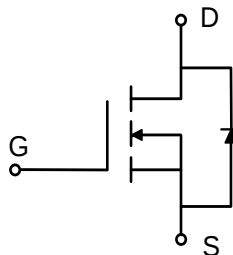
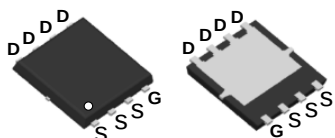


SGT N-Channel Power MOSFET

MTR4R4N03D33 PDFN3*3



V_{DS}	30	V
$R_{DS(on),max}@ V_{GS}=10\text{ V}$	4.4	mΩ
I_D	70	A

Features

- 1、Low on – resistance
- 2、High power package (PDFN3*3)
- 3、SGT N-channel Power MOSFET
- 4、Halogen free

Applications

- 1、Power Management Switches
- 2、DC/DC Converter

Maximum ratings, at $T_A=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		30	V
V_{GS}	Gate-Source voltage		± 20	V
I_D	Continuous drain current @ $V_{GS}=10\text{V}$	$T_C=25^\circ\text{C}$	70	A
		$T_C=100^\circ\text{C}$	44	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ\text{C}$	280	A
E_{AS}	Avalanche energy, single pulsed ②		45	mJ
P_D	Maximum power dissipation	$T_C=25^\circ\text{C}$	33.8	W
T_{STG}, T_J	Storage and Junction Temperature Range		-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Rating	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	3.7	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	60	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
--------	-----------	-----------	------	------	------	------

Static Electrical Characteristics @T_j=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1	1.6	2.2	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A	--	3.4	4.4	mΩ
		V _{GS} =4.5V, I _D =10A	--	4.6	6.5	mΩ
g _{fs}	Forward Transconductance	V _{DS} = 10V, I _D = 20A	--	90	--	S

Dynamic Electrical Characteristics@T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V , f=1MHz	--	1110	--	pF
C _{oss}	Output Capacitance		--	428	--	pF
C _{rss}	Reverse Transfer Capacitance		--	33	--	pF
R _g	Gate Resistance	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	--	1.1	--	Ω
Q _g	Total Gate Charge	V _{DS} =15V, I _D =20A , V _{GS} =10V	--	18	--	nC
Q _{gs}	Gate-Source Charge		--	3.2	--	nC
Q _{gd}	Gate-Drain Charge		--	2.5	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DD} =15V, V _{GS} =10V I _D =20A, R _G =3Ω,	--	6.1	--	ns
Tr	Turn-on Rise Time		--	4	--	ns
Td(off)	Turn-Off Delay Time		--	16.9	--	ns
Tf	Turn-Off Fall Time		--	4.4	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

VSD	Forward on voltage	I _S =20A, V _{GS} =0V	--	--	1.2	V
Trr	Reverse Recovery Time	I _F =20A	--	35.6	--	ns
Qrr	Reverse Recovery Charge	di/dt=100A/μs	--	10.8	--	nC

NOTE: ① Repetitive rating; pulse width limited by junction temperature T_{J(MAX)}=150°C.

② The test condition is V_{DD}=25V, V_{GS}=10V, L=0.4mH, I_{AS}=15A.

Typical Characteristics

Figure 1. Output Characteristics

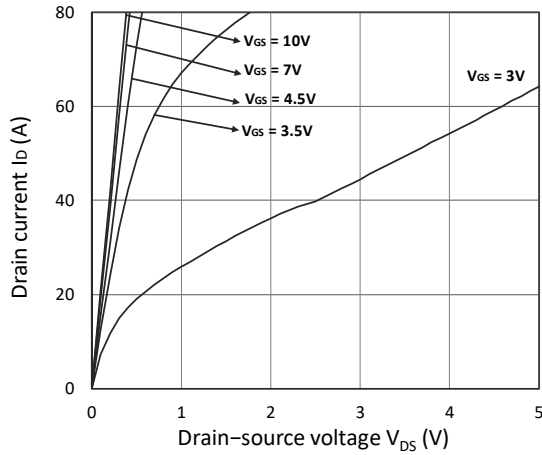


Figure 2. Transfer Characteristics

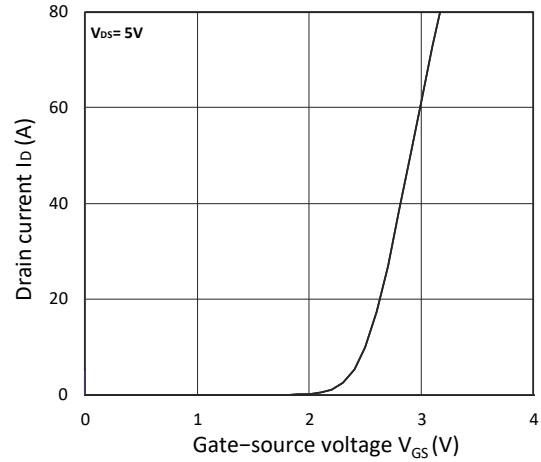


Figure 3. Forward Characteristics of Reverse

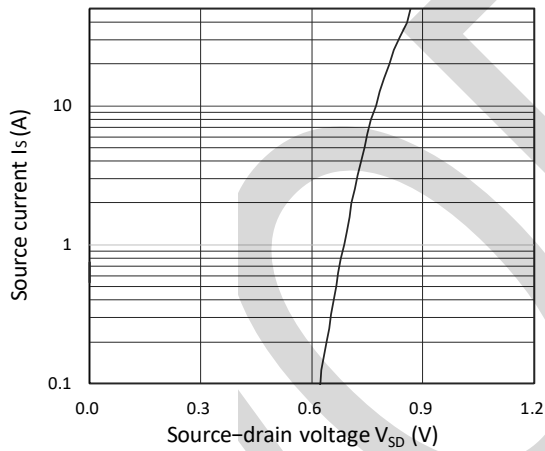


Figure 4. $R_{DS(on)}$ vs. V_{GS}

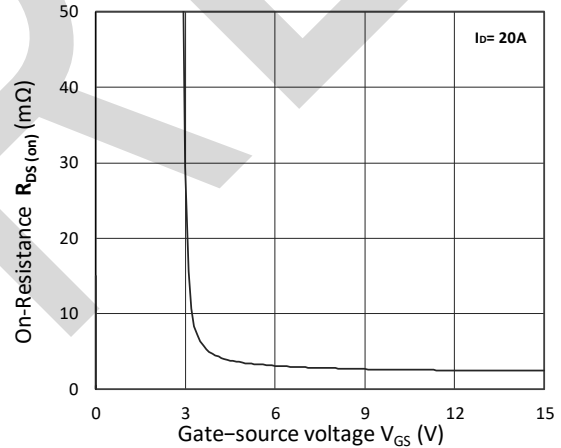


Figure 5. $R_{DS(on)}$ vs. I_D

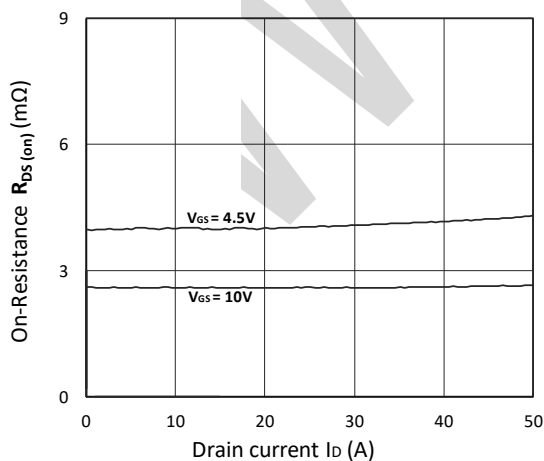
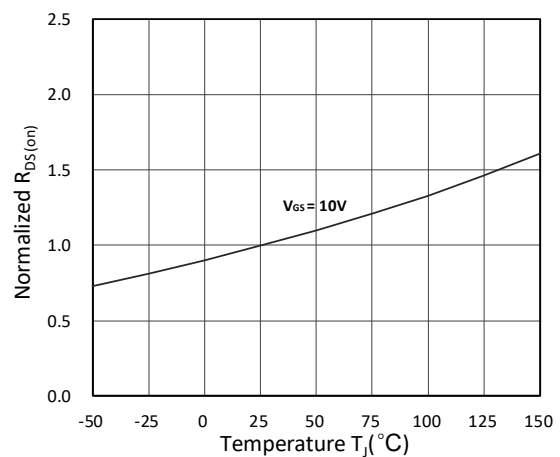


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



Typical Characteristics

Figure 7. Capacitance Characteristics

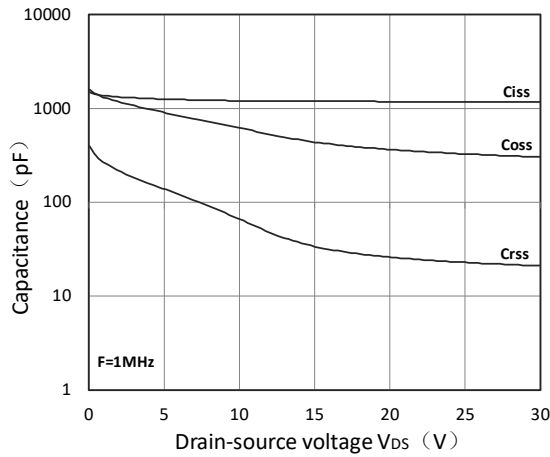


Figure 8. Gate Charge Characteristics

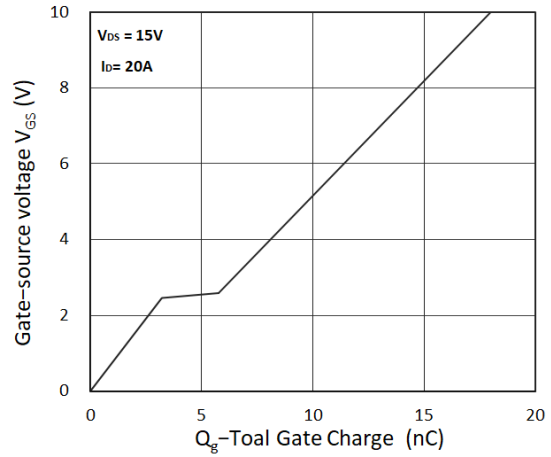


Figure 9. Power Dissipation

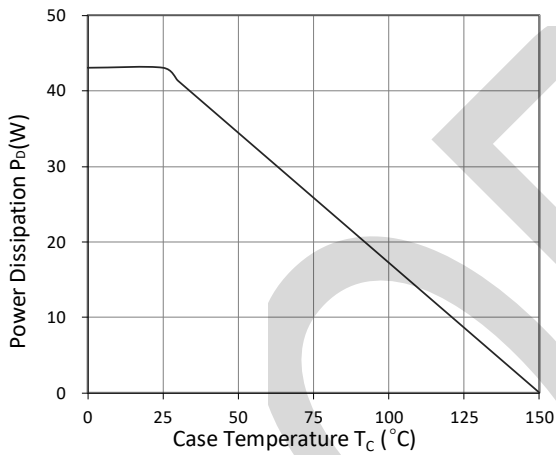


Figure10. Safe Operating Area

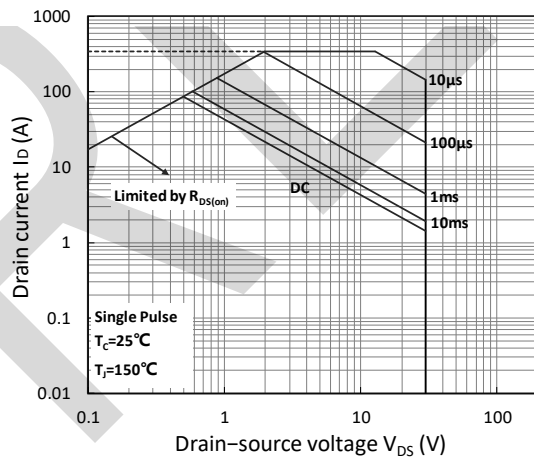
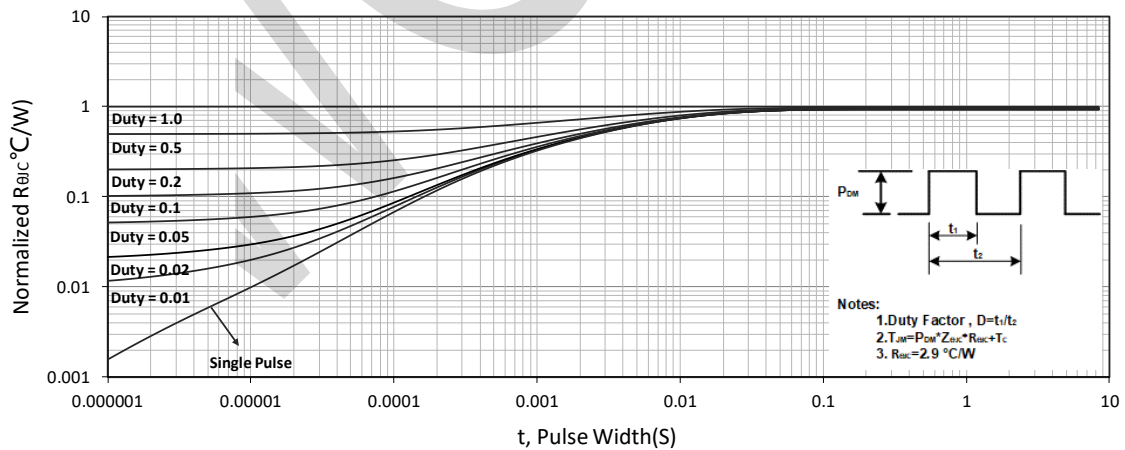
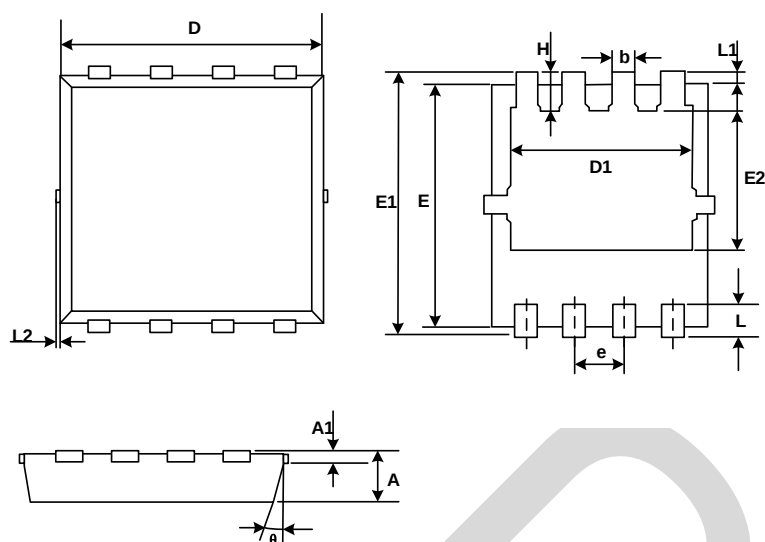


Figure 11. Normalized Maximum Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS

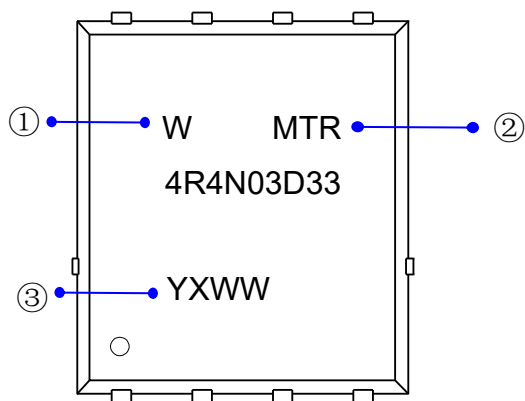


COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	0.65	0.90
A1	0.10	0.25
D	2.90	3.25
D1	2.25	2.69
E	2.90	3.20
E1	3.00	3.60
E2	1.35	2.20
b	0.20	0.40
e	0.65BSC	
L	0.15	0.50
L1	0.13BSC	
L2	0.00	0.20
H	0.15	0.65
θ	0°	14°

PACKAGE OUTLINE DIMENSIONS

Marking Information



①W : Company's trademark

②Product model : MTR4R4N03D33

③PDC information :

Y X WW

WW:Week code(01 to 53)

X:Internal identification code

Y:Year code(ex:0=2020)